

We Claim:

1. A semiconductor component, comprising:

a surface coating formed as an antifrictional layer for providing protection against scratches and mechanical abrasion;

said antifrictional layer being formed from a combination of materials selected from the group consisting of fats, oils, surfactants, and waxes; and

said antifrictional layer having an upper side forming a supporting surface of a fingerprint sensor for sensing a finger pad.

2. The semiconductor component according to claim 1, wherein said antifrictional layer contains a silicone oil.

3. The semiconductor component according to claim 2, wherein said antifrictional layer contains a perfluoropolyether.

4. The semiconductor component according to claim 1, wherein said antifrictional layer contains a perfluoropolyether.

5. A semiconductor component, comprising:

a surface coating formed as an antifrictional layer;

said antifrictional layer being an emulsion including water, paraffin oil, propylene glycol, stearic acid, palmitic acid, triethylamine, beeswax, carbomer 954, methylparaben and propylparaben.

6. The semiconductor component according to claim 4, comprising:

a passivation layer having an upper side;

said passivation layer being a layer selected from the group consisting of a polyimide layer, a silicon oxide layer, a silicon nitride layer, and a double layer having a silicon oxide layer and a silicon nitride layer;

said antifrictional layer protecting said upper side of said passivation layer against scratches and mechanical abrasion; and

said antifrictional layer having an upper side forming a supporting surface of a fingerprint sensor provided for sensing a finger pad.